ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES®	C. Bannockt	ourn. Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration en declaration	on of the su compasses	bstances w all lower	vithin the manufactu level materials for w	rer listed it hich the m	em. Note: anufacture	if the item is an as r has engineering	sembly with low responsibility.
				Form Type Distribute	*	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg					fg Informat	tion	
upplier Information													
Company name* Comp			ompany unique ID			Unique ID Authority				Response Date*			
onsemi									2023-06-08				
tact Name Title - Contact				]	Phone - Contact*				Email - Contact*				
Product-Env-Stewards Product Enviro			viro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repre			esentative			Phone - Representative*			Email - Representative*				
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Requester Item Number Mfr Item Nu		Number Mfr Item Name			Effective Date	Version	М	lanufacturing Site	7	Weight*	UOM	Unit Type
	LE25U4	LE25U40CQH-AH S-Flash Memory(4		(4M)		2023-06-08		CI	CNH		34.43	mg	Each
Ianufacturing Proccess Informat	ion		·			•	·			·			
Terminal Plating / Grid Array Ma	terial 7	rial Terminal Base Alloy J-S			Rating	Peak Process Body Temperature Max Time at I			e Max Time at Peak	k Temperature Number of Reflow Cycles			
Matte Tin (Sn) - annealed CU Alloy			3		260		С	30	secon	ds 3			
omments													
<b>FTENTION: MSL 3 Rated item requires</b>	Bake and D	ry Pack (after	electrical test)										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).							
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.06	mg	Supplier	Silicon (Si)	7440-21-3		2.0454	mg
			Supplier	Polyimide	Proprietary Data		0.0146	mg
Die Attach	0.5	mg	Supplier	Silver (Ag)	7440-22-4		0.3725	mg
			Supplier	Epoxy resins	129915-35-1		0.0425	mg
			Supplier	Polybutadiene polymer	Proprietary Data		0.01	mg
			Supplier	Acrylic resins	Proprietary Data		0.075	mg
Lead Frame	18.48	mg	Supplier	Silver (Ag)	7440-22-4		0.4602	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0351	mg
			Supplier	Iron (Fe)	7439-89-6		0.4675	mg
			Supplier	Copper (Cu)	7440-50-8		17.4913	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0259	mg
Mold Compound-Black	12.95	mg		Phenolic Resin	proprietary data		0.518	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		0.8417	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0388	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.5514	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Au	0.05	mg	Supplier	Gold (Au)	7440-57-5		0.05	mg